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MC9S12G Family Reference Manual and Data Sheet

S12
Microcontrollers


MC9S12GRMV1

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A full list of family members and options is included in the appendices.

The following revision history table summarizes changes contained in this document.


Revision History

Date	Revision Level	Description
Nov, 2012	1.18	<ul style="list-style-type: none"> Added Chapter 12, "Analog-to-Digital Converter (ADC12B8CV2)" Added Chapter 14, "Analog-to-Digital Converter (ADC12B12CV2)" Updated Chapter 11, "Analog-to-Digital Converter (ADC10B8CV2)" (Reason: Spec update) Updated Chapter 13, "Analog-to-Digital Converter (ADC10B12CV2)" (Reason: Spec update) Updated Chapter 15, "Analog-to-Digital Converter (ADC10B16CV2)" (Reason: Spec update) Updated Chapter 16, "Analog-to-Digital Converter (ADC12B16CV2)" (Reason: Spec update)
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This document contains information for all constituent modules, with the exception of the CPU. For CPU information please refer to **CPU12-1** in the **CPU12 & CPU12X Reference Manual**

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